Title (en)

Low profile high density sockets and related method of manufacturing

Title (de)

Niedrigprofilierte Buchsen hoher Dichte und entsprechendes Herstellungsverfahren

Title (fr)

Douilles à profil mince et à haute densité et méthode de fabrication y relative

Publication

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Application

EP 00122236 A 20001017

Priority

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Abstract (en)

The invention resides in an electrical connector (2) capable of being used in an array of contact element (12, 12', 12'') disposed between two parallel spaced apart plates defining a gap (70) into which the connector (2) is inserted. The connector (2) employs a plurality of spacer bars (14) on which are carried a plurality of contact rings which are spaced apart from one another by one or more spacer elements (16, 16'). The position of the contact elements (12, 12', 12'') can be readily varied from one spacer bar (14) to the other by the addition or elimination of one or more spacers to customize the contact array for adapting to the contact placement on the contact plates. Another embodiment of the invention may include using spacer rods made from an elastomeric material which can be stretched to allow the contact rings to be slid over a necked down portion of the rod (16). <IMAGE>

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